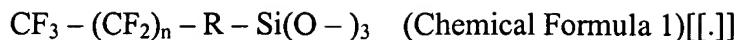


Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application. Claims 16-21 are canceled without prejudice or disclaimer.

Listing of Claims

1. (Currently Amended) A ceramic electronic component, comprising:
~~first and second two or more electrodes spaced at a predetermined distance from each other, the first and second electrodes being insulated from each other, a difference in potential being generated between the first and second electrodes during operation of the component, between which a potential difference is produced in operation and a void that penetrates to outside is provided the outside of the component being provided, and wherein a water repellent film is formed in the void.~~
2. (Original) The ceramic electronic component according to claim 1, wherein the formation of an electrical path is prevented by the water repellent film.
3. (Original) The ceramic electronic component according to claim 1, wherein the void is at least one selected from a minute hole and a defect.
4. (Currently Amended) The ceramic electronic component according to claim 2, wherein the water repellent film is formed only in the void between the two or more electrodes in said void is present only between the first and second electrodes.
5. (Original) The ceramic electronic component according to claim 1, wherein the water repellent film is formed of a residue resulting from a molecule of a coupling agent and has such a thickness as not to narrow the void by not less than 1 nm.
6. (Original) The ceramic electronic component according to claim 5, wherein the molecule of the coupling agent is bonded to a ceramic base material by a covalent bond.
7. (Original) The ceramic electronic component according to claim 5, wherein the molecule of the coupling agent has a portion containing a fluoroalkyl group
8. (Currently Amended) The ceramic electronic component according to claim 7, wherein the molecule of the coupling agent containing the fluoroalkyl group is a residue of perfluoroalkyl alkylsilane represented by the following general formula (Chemical Formula 1):



(n: 0 or an integer, R: a substituent containing an alkylene group, or a Si or oxygen atom).

9. (Original) The ceramic electronic component according to claim 7, wherein the molecule of the coupling agent containing the fluoralkyl group is polymerized.

10. (Original) The ceramic electronic component according to claim 1, wherein ceramic is formed by at least one selected from the group consisting of sintering after printing, sintering after sheet forming, vapor deposition, and sputtering.

11. (Currently Amended) The ceramic electronic component according to claim 1, wherein the ~~two or more~~ first and second electrodes are buried in an inner portion of ceramic or integrated on the surface.

12. (Currently Amended) The ceramic electronic component according to claim 1, wherein the electronic component is a thick film ceramic electronic component including a ceramic layer and ~~at least two~~ the first and second electrodes, the ceramic layer being formed as a thick film on a base material.

13. (Original) The ceramic electronic component according to claim 1, wherein the electronic component is a composite inductor component including a ceramic sintered body and at least two conductive circuits.

14. (Original) The ceramic electronic component according to claim 13, wherein the composite inductor component has a porosity ranging from not less than 2% to not more than 30%.

15. (Original) The ceramic electronic component according to claim 1, wherein the electronic component is at least one selected from the group consisting of a multilayer ceramic capacitor, a varistor, a semiconductive ceramic capacitor, a ceramic thermistor, an inductor array, a common-mode choke coil, a micro-transformer, and a ceramic electronic substrate housing a ceramic electronic function unit including two or more electrodes between which a potential difference is produced in operation.

16-21. (Canceled)